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1 Mapping the thermal entrenchment behavior of Pd

2 nanoparticles on planar SiO₂ supports

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8 Abstract

9 Thermal treatment of metal nanoparticles at temperatures above 1000 °C lead to the formation of nanopores in amorphous SiO₂ planar supports. In this work, we employ 10 11 Pd/SiO₂ as a model system to investigate how the initial size and distribution of nanoparticles on the SiO₂ surface affects the behavior of the nanoparticles at high 12 temperatures with respect to the formation of nanopores and related structures. We also 13 examine the role of physical processing parameters such as heating temperature, ramp 14 rate, and heating time in altering the type, size, and number density of features formed. 15 16 These studies reveal that nanopore formation competes with other surface phenomena, including nanoparticle agglomeration and encapsulation, which also occur at high 17 temperatures. We establish that the dominant behavior, among the many competing 18 19 phenomena occurring at the metal-oxide interface, depends on the initial surface distribution of the nanoparticles. Using this knowledge, we show that the final nanopore 20 21 diameter and surface density are highly tunable.

22 **1. Introduction**

Metal-oxide and metal-metal interactions, especially at high temperatures, are of 23 critical importance in catalysis¹⁻⁴ and electronics.^{5,6} The metal-oxide interface is a 24 25 catalytically active site for many industrially important reactions. At high temperatures, catalyst deactivation can occur via sintering or encapsulation due to surface 26 rearrangement at the metal-oxide interface.^{7–11} Similarly, thin films of metals deposited 27 on oxide layers are used for the fabrication of electronic devices where the metal-28 semiconductor interface is of significance.^{12,13} At high temperatures, the stability of these 29 films is reduced by dewetting.^{14–17} Thus, the understanding of metal-oxide interactions at 30 high temperatures is important for designing stable catalysts and electronic devices. To 31 this end, these interactions have been studied for a wide range of metals (Au, Pd, Pt, Cu) 32 and oxides (TiO₂, SiO₂, Al₂O₃) across different temperature ranges.^{7-9,12,13,18-24} At 33 elevated temperatures (above 600 °C) metal-oxide interactions, especially for metal 34 nanoparticles, lead to a wide range of behaviors including agglomeration,^{7,25} Ostwald 35 36 ripening,^{7,20} diffusion,^{26,27} reaction,^{11,28} encapsulation,^{9,18} and in some instances, nanopore formation.^{29–32} In this work, we demonstrate that, at conditions where multiple 37 38 phenomena are kinetically favored, the extent to which each of these will occur depends upon the size and surface density of the metal nanoparticles as well as the thermal 39 conditions employed. 40

Nanopore formation, predominantly observed for metal nanoparticles on amorphous SiO₂, occurs at very high temperatures (>1000 °C).^{29–32} This behavior is also described here as nanoparticle entrenchment since, in some cases, metal nanoparticles have been shown to persist at the bottom of the pores.³¹ Nanopores and embedded

45 nanoparticles formed in this manner can be used in separations, catalysis, and electronics.^{29,33–35} In this work, we employ Pd nanoparticles supported on planar SiO₂ as 46 a model system to study nanopore formation and entrenchment behavior as a function of 47 48 different heating conditions (temperature, time, and ramp rate) and initial surface 49 distributions (nanoparticle size and surface density). Of all the metals that have exhibited 50 nanopore formation (Au, Aq, Cu, Pd, and Pt), Pd nanoparticles entrench the most rapidly (within 10 minutes of heating) and tend to form linear nanopores thus making them ideal 51 candidates for a study of this kind.²⁹ Planar SiO₂ was used rather than high surface area 52 53 silica particles to avoid interference from pre-existing surface porosity on high surface 54 area particles and to gain additional insights by using techniques like atomic force 55 microscopy (AFM) to reimage the same spot after chemical and thermal different treatments. In general, the Pd/SiO₂ system has been thoroughly studied for different 56 behaviors at high temperatures due to its relevance to the field of catalysis.^{19,36–38} 57 Additionally, the low solubility of Pd in the SiO₂ matrix²⁷ minimizes potential Pd loss by 58 59 diffusion into SiO₂.

In our previous work, we proposed a mechanism for nanopore formation that is 60 61 observed when metal nanoparticles supported on amorphous SiO₂ are heated to temperatures above 1000 °C. At high temperatures (above 900 °C), the solubility of 62 metals in the SiO₂ matrix is significant, and when the metal atoms diffuse into SiO₂, they 63 lower its glass transition temperature (T_q). At temperatures above the T_q (~1000 °C), SiO₂ 64 exhibits viscoelastic behavior, allowing the nanoparticles to form nanopores.²⁹ It has also 65 66 been proposed that the slow evaporation of the metal nanoparticles at the surface causes the continuous renewal of the metal-SiO2-vapor interface and prevents the total 67

encapsulation of the metal nanoparticle within the SiO_2 matrix.³¹ In the case of Au nanoparticles, the Au (111) plane of the nanoparticle is expected to not melt, which pins the nanopore and prevents its closing/pinching.³¹

71 When metal nanoparticles entrench within the SiO_2 surface at high temperatures, they 72 form nanopores that could extend through the entire thickness of the SiO₂ layer. We 73 previously showed that nanopore formation occurs only above a certain minimum temperature (1000 °C for Au nanoparticles).²⁹ Additionally, the nanoparticles, depending 74 on their composition and size, require different temperatures and heating times to 75 entrench.²⁹ The resulting nanopores are characterized by two features: its pore diameter 76 77 and the height of its oxide ridge. The oxide ridge surrounding the nanopore is formed as a result of oxide transport occurring due to the shifting surface energy equilibrium at the 78 metal-oxide-gas triple line.^{17,31} Understanding how phenomena such as agglomeration, 79 diffusion, and encapsulation, also occurring at these high temperatures, compete with 80 81 nanopore and oxide ridge formation will provide a fundamental understanding of the 82 metal-oxide interactions that lead to nanopore formation. Moreover, this will also help define synthesis conditions for nanopores of desired dimensions. Here, we first examine 83 84 Pd nanoparticles with different initial sizes (1.5 - 25 nm) and surface densities (5 - 7000 mm)nanoparticles/µm²) and establish how the initial surface distribution of the nanoparticles 85 defines the final size and surface density of the nanopores. 86

To understand the role of thermal processing in nanopore formation, several representative initial distributions of the Pd/SiO₂ system were further studied under different heating conditions (temperature, hold time, and ramp rate). The features observed after heating include nanopores, partially embedded nanoparticles,

91 agglomerated nanoparticles without nanopore formation, and nanoparticles encapsulated in SiO₂. We observe that the types of surface features present after heating depend on 92 the initial size and surface density of the nanoparticles. We also show that tuning the 93 94 initial size and surface density of Pd nanoparticles on SiO₂ controls the nanopore diameter and height of the surrounding oxide ridge. The interplay of agglomeration and 95 96 nanopore formation limits the maximum surface density of nanopores to ~150 nanopores/µm², but a range of nanopore sizes (5 - 25 nm) are observed depending on 97 the initial particle size distribution. 98

99 **2. Methods**

100 a. Nanoparticle synthesis

Randomly distributed Pd nanoparticles on SiO₂ surfaces were synthesized using block 101 copolymer micelle lithography.^{39–41} Aqueous solutions of Pd-containing micelles were 102 103 synthesized by combining the diblock copolymer, polyethylene oxide-b-polyvinyl pyridine (PEO-*b*-P2VP) of varying chain lengths (Table S1, Polymer Source, Inc.) and Na₂PdCl₄ at 104 105 different pyridyl: Pd molar ratios (32:1, 16:1, 8:1, 4:1, 2:1, 1:1, and 0.5:1) and shaking 106 overnight. The solution pH was maintained between 3-4 by adding dilute HCI. Thin films 107 of the Pd-containing micelle solution were spin-cast on Si wafers (NOVA Electronic Materials, 285 nm thermal oxide) at different rotation speeds (1000 RPM, 2000 RPM, 108 3000 RPM, and 4000 RPM). Some of the samples were treated with oxygen plasma for 109 110 different intervals (1 min, 2 min, 3 min, and 5 min) (Plasma Etch Inc., PE 50XL, 30 W) to 111 control the surface densities of Pd nanoparticles. The Pd-containing micelles were then reduced to nanoparticles by thermal annealing in a tube furnace (ThermoScientific Blue) 112 113 under flowing argon gas (195 sccm; ramp 4 °C/min to 150 °C, hold for 10 h) and then

flowing H₂ gas (195 sccm; ramp 11 °C/min to 500 °C, hold for 10 h). The resulting Pd nanoparticles (Pd/SiO₂) have sizes ranging from 1.5 - 25 nm and surface densities from 5 - 7000 nanoparticles/ μ m². A detailed description of the initial Pd nanoparticle sizes and distributions resulting from different synthesis conditions is included in the supplementary materials and illustrated in Figure S1.

119

120 b. Rapid thermal processing (RTP)

Heating of the Pd/SiO₂ was performed under flowing Ar (100 sccm) in a rapid thermal processing (RTP) furnace (MTI Corporation, OTF-1200X-4-RTP-UL). Most samples were treated at 1040 °C for 10 min using a ramp rate of 3.3 °C/s from room temperature. However, ramp rates were varied between 0.33 and 3.3 °C/s, hold temperatures between 850 and 1040 °C, and hold times between 1.5 and 20 min. The samples were passively cooled to room temperature under flowing Ar (25 sccm). The furnace cooled from ~1000 °C down to 480 °C in less than 5 min, while 480 °C to room temperature took ~ 2 h.

128 c. Surface features and composition characterization

Atomic force microscopy (AFM) was performed on a FastScan (Bruker) using FastScan 129 130 C probes. AFM image analysis and quantitative measurements were performed using the Nanoscope Analysis software (Bruker). For increased accuracy in scanning the same 131 132 sample at different stages of synthesis and thermal treatment, a light scratch mark was 133 made with a diamond pen and AFM imaging was performed at a known distance from the 134 mark. For the nanoparticle distributions with a low surface density of nanoparticles, the 135 nanoparticle height and radius are comparable and remain fairly unchanged at elevated 136 temperatures. In these cases, the nanoparticle heights reported by the software are

137 defined as the standard nanoparticle size since the nanoparticle diameters detected by the AFM could be erroneous due to tip convolution effects.⁴² However, for nanoparticle 138 139 distributions that have a very high surface density, particle coalescence occurs at 140 elevated temperatures.⁷ In these cases, the agglomerated nanoparticles form islands that have very disparate diameters and heights. For such distributions, nanoparticle diameters 141 142 are considered as the standard size. Nanopore diameters are defined as the standard nanopore size since the depth of the nanopore cannot be determined accurately using 143 144 AFM.

145 The Pd nanoparticle surface coverage is defined as the percent of the SiO₂ surface in 146 contact with the Pd nanoparticles. AFM images are processed in the software Image J, and a Pd-SiO₂ contact angle of 90° or less is assumed. The Pd/SiO₂ surface composition 147 was analyzed before and after RTP using X-ray photo-electron spectroscopy (XPS) 148 equipped with an Al-source with a spot size of 500 µm (ThermoScientific, Escalab 250 149 150 Xi). To study the surface profile of the oxide ridges around partially embedded Pd 151 nanoparticles, the surfaces were etched using a Pd etchant solution (Transene) before imaging the surface via AFM. 152

153 **3. Results and Discussion**

a. Different behaviors observed at high temperatures

After subjecting the library of Pd/SiO₂ surfaces to rapid thermal processing (RTP) consisting of a ramp to 1040 °C at rate 3.3 °C/s followed by a hold at that temperature for 10 min, we observe different surface features. For most initial Pd nanoparticle distributions, a variety of surface features showing Pd nanoparticles in various stages of entrenchment are observed (Figure 1). For a representative distribution, we observe that

160 the nanoparticles agglomerate before they entrench. This is apparent because the initial surface has ~600 nanoparticles/ μ m² with an average height of 6.5 nm ± 2.8 nm, while the 161 162 final distribution after RTP has ~60 features/µm², including both nanopores and 163 nanoparticles in various stages of entrenchment (Figure 1A and B). The commonly observed surface features include agglomerated (but not entrenched nanoparticles), 164 partially and near-completely entrenched nanoparticles, and nanopores (Figure 1C). 165 Each of these features is accompanied by oxide ridge formation around both the 166 167 nanoparticles and nanopores. Additionally, we also observe positive surface features that 168 cannot be removed by metal etching, which indicate the encapsulation of the Pd 169 nanoparticles by SiO₂ that has become mobile at these temperatures. To quantify these different behaviors, we define two non-dimensional parameters: pore fraction (f_{Pore}) and 170 extent of agglomeration (E_{Agg}) (Equations 1 and 2, respectively). 171

172
$$f_{Pore} = 100 \times \left(\frac{Number of nanopores / \mu m^2}{Total number of features (nanopores + nanoparticles) / \mu m^2}\right)$$

173
$$E_{Agg} = 100 \times \left(1 - \frac{Final number of features(nanopores + nanoparticles) \ per \ \mu m^{2}}{Initial number of nanoparticles \ per \ \mu m^{2}}\right)$$

174 For very small nanoparticles with low surface densities (size < 2 nm, surface 175 density < 150 nanoparticles/ μ m²), the surface features after RTP become 176 indistinguishable from the surface roughness (± 1 nm) of the SiO₂ layer (Figure S2). The nanoparticles may either be diffusing into the substrate²⁷ or evaporating.⁴³ On the other 177 hand, RTP of large nanoparticles with high surface densities (size ~ 7 nm, surface density 178 ~ 4000 nanoparticles/ μ m²) such that the nanoparticles form multilayers, results in 179 180 overlapping nanopores in the SiO₂ substrate (Figure S3). These two extreme distributions are excluded from consideration. In the majority of other cases, the final surface features 181

are readily counted and characterized. In these cases, decreases in the number density of the features ($E_{Agg} > 0$) are accompanied by increases in the size of the remaining features. For cases where no nanopores form, the total volume of the Pd-containing surface features is approximately conserved after RTP (Table S2), confirming that agglomeration of small particles into larger ones is the primary pathway for loss of surface feature number density.

The surface speciation after RTP (hold at 1040 °C for 10 min and a ramp rate of 188 3.3 °C/s) is shown in Figure 2A as a function of different initial surface distributions. As 189 190 discussed above, four different behaviors were identified and quantified across the entire 191 range: 1) complete entrenchment, 2) partial entrenchment, 3) agglomeration (with no 192 entrenchment during the heating time allotted), and 4) encapsulation. The different ranges of E_{Agg} and f_{Pore} used to define these behaviors are illustrated in Figure 2B. These 193 behaviors are observed across the entire range of initial nanoparticle size and surface 194 195 densities considered (Figure S5).

196 Since we previously showed the RTP of metal nanoparticles at temperatures such as employed here produce nanopores, it is not surprising that complete nanoparticle 197 entrenchment ($f_{Pore} > 75\%$ and $0 < E_{Agg} < 100\%$) is the most frequently observed 198 199 outcome.^{29,31} Complete entrenchment is accompanied by the formation of oxide ridges around the nanopores. Even though the nanopore depth cannot be quantified using AFM 200 201 due to tip-size limitations, we have previously employed cross-sectional electron 202 microscopy to show that under these RTP conditions, most nanopores extend the entire thickness of the SiO₂ layer (285 nm in this case).²⁹ In addition to complete entrenchment, 203 partial entrenchment ($10\% < f_{Pore} < 75\%$ and $0 < E_{Agg} < 100\%$) is also observed. In these 204

205 cases, some nanoparticles form nanopores, while others only partially entrench or do not entrench to an observable extent during the heating time. The third behavior, 206 agglomeration (not accompanied by nanopore formation; $10\% < f_{Pore}$ and $E_{Aaa} > 10\%$) is 207 208 characterized by a reduction in the nanoparticle surface density and a corresponding 209 increase in nanoparticle height, without any apparent entrenchment. This presumably 210 occurs when lateral mobility on the surface is favored over entrenchment within the annealing time (10 min). However, after longer annealing, both the partially entrenched 211 212 and agglomerated nanoparticles result in nanopore formation (Figure S6). This indicates 213 that the rate of nanopore formation in these cases is slowed, but not prohibited. However, 214 for some initial nanoparticle distributions, neither nanopore formation nor agglomeration 215 are observed ($f_{Pore} < 10\%$ and $E_{Aag} < 10\%$), even after extended heating. As discussed 216 below, these features are characterized as Pd nanoparticles that have been encapsulated by SiO₂. 217

218 Examining the data in aggregate, several conclusions can be made. First, nanopore 219 formation, with partial or complete entrenchment, occurs across almost the entire range of initial nanoparticle sizes and surface densities (Figure S4). Second, Pd surface 220 221 coverages appear to be critical. Coverages above 20% always result in agglomeration, with or without nanopore formation (Figure 3), whereas coverages below 20% rarely 222 agglomerate before entrenchment. Surface area coverage is a function of both the 223 224 nanoparticle size and surface density such that large nanoparticles with low surface 225 density (e.g. 12 nm and 80 nanoparticles/ μ m²) have the same surface area coverage 226 (8.5%) as that of small nanoparticles with high surface density (e.g. 3 nm and 750 nanoparticles/µm²). Low coverages and higher surface densities favor agglomeration 227

before nanopore formation. The two parameters can generally predict the dominant
behavior upon RTP (complete entrenchment, partial entrenchment, agglomeration, or
encapsulation).

231 Surfaces of particular interest from the perspective of materials design are those 232 for which the sizes and surface densities of the final features are very similar to the initial nanoparticles availing a greater predictability and control. For this purpose, $E_{aaa} < 20\%$ is 233 234 desirable. These all have nanoparticle surface coverages < 20% (Figure 4), specifically, 235 initial nanoparticle distributions of 4 - 25 nm and 5 - 450 nanoparticles/ μ m². These surface 236 densities correspond to interparticle spacings of 30 - 60 nm, which appear to be large 237 enough to minimize agglomeration. Within this region, < 5% Pd surface coverage (i.e. 6 - 25 nm nanoparticles and 5 – 350 nanoparticles/ μ m²) primarily results in complete or 238 239 partial entrenchment after 10 min at these RTP conditions, as the nanoparticles are large 240 enough to resist encapsulation (Figure 4B). In contrast, nanoparticle encapsulation is observed at 5 – 15% surface coverage (i.e. smaller 4 – 8 nm nanoparticles with 250 – 241 450 nanoparticles/ μ m²) (Figure 4A). Thus, in the absence of agglomeration, the 242 entrenchment (complete or partial) and encapsulation are the two dominant behaviors 243 244 and occur over mutually exclusive ranges of initial nanoparticle distributions. No attempt 245 is made to identify distributions that favor complete entrenchment over partial 246 entrenchment, since the latter can be eliminated by continued heating.

Overall, these considerations allow us to predict the dominant behaviors for various sizes and surface densities after RTP. We expect larger nanoparticles (10 - 25 nm) with low surface densities (< 200 nanoparticles/ μ m²) to form nanopores without agglomeration. Similarly, smaller (1 - 10 nm) nanoparticles with high surface densities

251 (100 - 7000 nanoparticles/ μ m²) are highly mobile and will agglomerate before 252 entrenchment. Nanoparticles with distributions between these two extremes (4 - 8 nm 253 nanoparticles and 250 - 450 nanoparticles / μ m²) will be encapsulated within the SiO₂ 254 support.

b. Understanding encapsulating behavior

256 While most nanoparticle distributions studied here ultimately lead to nanopore 257 formation, we noted above that some nanoparticle distributions remain unchanged after 258 RTP, with no apparent nanopore formation (Figure 5A i-ii). Additionally, the surface 259 features do not undergo further transformation upon extended heating, unlike the partially 260 entrenched or agglomerated nanoparticles (Figure 5A iii). Furthermore, the surface 261 features remaining after RTP have approximately the same size, number density, and 262 spatial arrangement as the initial Pd nanoparticles (Figure S8). However, for these 263 samples, the Pd XPS signals are lost after RTP (Figure 5B). The conclusion most 264 consistent with all these observations is that the Pd nanoparticles are encapsulated by a 265 layer of SiO₂, which acts as barrier to entrenchment.

It has been reported that strong metal-surface interactions (SMSI) lead to 266 encapsulation of metal nanoparticles in reducible oxides.^{8,10,18} To investigate if certain 267 268 distributions of Pd nanoparticles become encapsulated by SiO₂, samples were treated 269 with a Pd etchant following RTP. For the nanoparticle distributions where no apparent 270 change was observed after RTP, the surface topology also remained unchanged after the Pd etch (Figure 5A iv) indicating that some protective layer, assumed to be SiO₂, exists 271 272 over the features. In cases where the Pd nanoparticles were partially embedded in the 273 support, Pd etching reveals only the oxide ridges formed around the nanoparticles (Figure

S7). The SMSI effect is typically reported to be almost negligible for Pd/SiO₂,⁹ in contrast 274 it is strong for Pd on other reducible oxides (e.g. Al₂O₃ or TiO₂). However, most studies 275 276 are carried out far below 1000 °C. Under RTP conditions, Pd diffuses into the SiO₂ and 277 causes the support to become viscoelastic.²⁹ At this point, the SiO₂ is sufficiently mobile 278 to fully encapsulate the nanoparticles during oxide ridge formation (Scheme 1A). It is also 279 possible that the nanoparticles do entrench, but that the oxide ridges are sufficiently large to close off the nanopore (Scheme 1B). In each scenario, neither the nanoparticle nor the 280 nanopore are accessible, effectively resulting in nanoparticle encapsulation. 281

282 c. Entrenchment at different heating conditions

283 Previously, we reported that 10 - 15 nm Au nanoparticles required temperatures > 1000 °C and hold times > 10 min to form nanopores in SiO₂,²⁹ but Ag nanoparticles of the 284 285 same size entrenched at ~900 °C. In the previous sections, we saw that the nature of entrenchment depends on the initial nanoparticle distribution and the competition 286 287 between nanopore formation and other surface phenomena. In this section, we report on 288 the evolution of nanopores under different RTP conditions (annealing time, temperature, and ramp rates) for two characteristic Pd/SiO₂ distributions: one with E_{Agg} < 20% (large 289 particles and low surface density) and another with $E_{Agg} > 80\%$ (small particles and high 290 surface density; see Figure S9). 291

292 (i) Effect of Hold Temperature

Two distributions of Pd/SiO₂ were studied following RTP (10 min hold times and ramp rates of 3.3 °C/s) using hold temperatures between 850 °C and 1040 °C. For a high surface density of small nanoparticles (3 - 4 nm and > 5000 nanoparticles/ μ m²), only agglomeration is observed at 850 and 900 °C. Here, the nanoparticle surface density

decreases from > 5000 to ~ 2000 nanoparticles/ μ m² and the nanoparticle size increases from ~ 3.5 to 6 nm after RTP (Figure 6). RTP at 950 °C shows further agglomeration such that the nanoparticle surface density decreases to 60 nanoparticles/ μ m² while the nanoparticle size increases five-fold. At hold temperatures of 1000 and 1040 °C, the agglomerated nanoparticles entrench into the SiO₂ surface, resulting in nanopores with diameters similar to the size of the agglomerated nanoparticles (Fig. 5B).

303 The behavior of Pd/SiO₂ with fewer, larger nanoparticles (6 - 7 nm and surface densities of ~200 nanoparticles/ μ m²) is significantly different (Figure 7). Since these 304 305 nanoparticles have larger interparticle spacings, agglomeration is not as common, and 306 the size and surface densities remain approximately constant after RTP at 850 °C and 307 900 °C. After 10 min at 950 °C, nanoparticle size and density do not significantly change, 308 but oxide ridge formation is observed around the Pd nanoparticles without complete entrenchment. This behavior is similar to what we previously reported for Au 309 310 nanoparticles of similar sizes and surface densities following RTP at 900 °C.²⁹ For this 311 Pd/SiO_2 distribution, nanopore formation begins at 1000 °C, although < 20% of the nanoparticles initially entrench. By 1040 °C nearly all nanoparticles form nanopores, and 312 313 the average diameter of the resulting nanopores is comparable to the initial nanoparticle 314 size. This case demonstrates that applomeration to a certain size is not a prerequisite for 315 nanopore formation in cases where agglomeration isn't kinetically favored. Indeed, of the 316 two cases compared here, the initially smaller nanoparticles first agglomerate and then form larger nanopores (Scheme 2A), while the initially larger, well-spaced nanoparticles 317 318 are fairly immobile and do not transform until subjected to entrenchment temperatures 319 (Scheme 2B), ultimately resulting in smaller nanopore diameters. For both distributions,

320 oxide ridge formation is observed at temperatures slightly below the onset of 321 entrenchment. Overall, agglomeration and entrenchment/nanopore formation are all 322 kinetically driven behaviors, and they depend on both temperature and initial nanoparticle 323 size. The kinetic activation barrier to entrenchment appears to be higher than those for 324 agglomeration and oxide ridge formation, thus explaining its dominance at the highest 325 temperatures.

326 (ii) Effect of Hold Time

The same two surface distributions of Pd/SiO₂ were studied to determine the effect of 327 328 hold time, following RTP with a ramp rate of 3.3 °C/s and a hold temperature of 1040 °C. 329 For a high surface density of small nanoparticles, only applomeration is observed during 330 the first 1.5 min (Figure 8). After 3 min, agglomeration remains dominant, but some 331 nanopores begin to form, and oxide ridges are observed around the nanoparticles. 332 Between 3 and 5 min, all the agglomerated nanoparticles entrench forming nanopores 333 whose average diameter and density is similar to that of the agglomerated nanoparticles. 334 While the nanopore depth cannot be determined using AFM, it was seen that the 335 nanoparticles have entrenched beyond the range of the tip. These observations prove 336 that, when both occur, entrenchment and agglomeration are sequential processes. At the 337 highest temperatures, small and highly mobile nanoparticles have high rates of 338 agglomeration. Once they grow to a certain size, the relative rate of entrenchment 339 increases, and nanopore formation starts. In contrast, for initially larger nanoparticles and 340 lower surface densities, agglomeration does not readily occur, instead nanopores form in 341 the first 1.5 min of RTP to 1040 °C with no other competing surface phenomena (Figure 342 9).

343 (iii) Effect of Ramp Rates

In addition to the RTP hold temperature and time, the temperature ramp rate 344 345 influences the nature of the resulting surface features. For both Pd/SiO₂ distributions 346 tested, a ramp rate of 0.33 °C/s to 1040 °C combined with a 10 min hold results in only 347 agglomeration and encapsulation with no distinct nanopores (Figure 10A i and B i). At 348 ramp rate of 1 °C/s however, small nanoparticles at high surface density undergo complete nanopore formation (Figure 10A ii), while the larger nanoparticles at low surface 349 350 density undergo distinct oxide ridge formation, but only partial entrenchment (Figure 10B 351 ii). Complete entrenchment is observed for both the nanoparticle distributions at a ramp rate of 3.3 °C/s. 352

In previous sections, we showed that agglomeration is dominant until 900 °C, oxide 353 354 ridge formation occurs at 950 °C, and nanopore formation starts at 1000 °C. With ramp 355 rates < 1 °C/s, the nanoparticles stay at temperatures favoring agglomeration and oxide 356 ridge formation for longer periods. In this situation, they may become encapsulated by tall 357 oxide ridges resulting from continuous oxide transport at the interface, and no distinct 358 nanopores are formed by the time they attain entrenchment temperatures. On the other 359 hand, ramp rates of 3.3 or 10 °C/s (Figure S10) minimize the residence time below 1000 360 °C and ensure distinct pore formation. It is important to note that the slowest ramp rate 361 we used (0.33 °C/s) is higher than standard ramp rates used in the preparation of catalytic 362 materials (e.g. 0.16 °C/s or 10 °C/min) thus explaining why nanopore formation has not 363 been readily observed in literature. Some prior reports have achieved nanopore formation 364 at lower ramp rates, but with initial particles sizes $\sim 1 \, \mu m$ resulting in nanopores of large 365 diameters (200 nm) and comparatively smaller oxide ridges (20 nm).³¹ However, in cases

where the height of the oxide ridge is comparable to the nanopore diameter, as considered in this work, large oxide ridges can undesirably close off nanopores or encapsulate the nanoparticles.

369

370 d. Nanopore formation on complete entrenchment

371 The nanopores formed through the method of high temperature entrenchment as demonstrated here, could have a wide range of applications depending on their diameters 372 and aspect ratios. As shown in the proceeding sections, the nanopore diameter and 373 374 surface density, as well the height of their surrounding oxide ridges, depend strongly on 375 the initial size and surface density of the nanoparticles and their resulting tendency to 376 agglomerate before entrenchment (Figure 11). Figure 11A and B show how the nanopore 377 diameter and the height of the oxide ridge surrounding it change with changing Pd nanoparticle size and surface density on SiO₂. Low surface densities of large 378 379 nanoparticles do not significantly agglomerate before entrenchment ($E_{Agg} < 20\%$) and 380 form nanopores with diameters and surface densities comparable to their initial 381 distribution. On the contrary, high densities of small nanoparticles undergo significant 382 agglomeration ($E_{Agg} > 80\%$) and eventually form nanopores with larger diameters of 10 -15 nm and significantly lower surface densities ($<200/\mu m^2$) than their initial distribution 383 384 before rapid thermal processing. This indicates that when agglomeration precedes 385 nanopore formation, the nanoparticles aggregate to a similar size and surface density before entrenchment, irrespective of their initial surface distributions. 386

We also observe that the oxide ridges are larger when the nanoparticles do not agglomerate, even when they produce comparable nanopore diameters (Figure 11B).

389 Since small nanoparticles are very mobile on the surface, the metal-oxide-vapor triple-390 line⁴⁴ is also mobile (Scheme 3A). Since the triple-line is the location of ridge formation, 391 individual ridges do not have as much time to grow as when the nanoparticle and triple-392 line remained fixed (Scheme 3B). Thus, if minimal oxide ridges are desired, it would be preferable to begin with high surface densities of small nanoparticles where 393 394 agglomeration occurs agglomerate before entrenchment. Different diameters and surface densities may be desired, depending on the application of the nanopores. Table S3 and 395 Figure S11 highlight the different nanopore distributions resulting from certain initial 396 397 nanoparticle distributions and RTP conditions, as may be useful to the practitioner to 398 design desired surface features.

399 **4.** Conclusions

400 At high temperatures, oxide-supported metal nanoparticles undergo a number of processes including aggregation^{7,12} and evaporation,⁴³ the mechanisms of which have 401 been extensively studied. At the same conditions, restructuring of the oxide surface has 402 403 also been observed, including encapsulation of the metal nanoparticle^{9,18} or the formation of nanopores (entrenchment).^{29–32,45,46} In our prior work we showed how entrenchment 404 405 depends on metal and oxide identity and on the temperature of the thermal treatment, but our and others findings were limited primarily to low particle surface densities (< 100 406 nanoparticles/µm²).^{29,31,32,45} In contrast, many studies on metal nanoparticle aggregation, 407 408 e.g. for applications in heterogeneous catalysis, have been carried out at much higher 409 surface densities.^{7,47,48} It has not been clear how to reconcile these two extreme 410 behaviors.

411 In this new study, we have shown that the competition between encapsulation, 412 entrenchment, and aggregation processes depend strongly on Pd nanoparticle surface 413 density and initial size. In particular we have established that small nanoparticles with 414 high surface densities (1-10 nm, 100-7000 nanoparticles/ μ m²), will agglomerate before 415 forming nanopores whereas large nanoparticles with low surface density (10-25 nm, < 416 200 nanoparticles/ μ m²), having very low surface mobility, will form nanopores of 417 comparable surface densities. We also report and explain a third behavior- nanoparticle 418 encapsulation. This behavior occurs for nanoparticles that do not have high enough 419 surface densities (250- 450 nanoparticles $/\mu m^2$) to favor agglomeration and their small 420 size (4-8 nm) allows for the SMSI between Pd and SiO₂ at high temperatures (above 1000 421 °C) to completely encapsulate the nanoparticles.

422 Having understood the different end behaviors at various sizes and surface 423 densities of Pd nanoparticles on SiO₂ substrates on RTP, we have further studied the 424 dependence of these phenomena on the heating conditions including temperature, time, 425 and ramp rates. We establish that the nanopore formation is kinetically driven and occurs 426 at a certain temperature and time above which increasing temperature and hold time 427 causes a greater extent in entrenchment. Of the two distributions studied here, 428 nanoparticles with smaller particle sizes and high surface densities (1-10 nm, 100-7000 429 nanoparticles/ μ m²), agglomerate first to a size of 20-25 nm and then proceed to form 430 nanopores of comparable sizes. The rate at which the nanoparticles distributions are 431 heated to entrenchment temperatures also plays a crucial role in the final surfaces 432 observed. When Pd nanoparticles are slowly heated to entrenchment temperature (< 1 433 °C/s) they have enough time to equilibrate with the supporting oxide and have a greater

434 tendency to form tall oxide ridges that ultimately encapsulate the nanoparticle or block off any nanopore that may form. However, when higher rates are employed, the 435 436 nanoparticles reach entrenchment conditions faster, bypassing encapsulation by 437 extensive oxide ridge formation. However, for surfaces where agglomeration is favored, nanoparticles will always proceed through that pathway before entrenchment. We thus 438 439 establish that although applomeration and nanopore formation are kinetically driven, oxide ridge formation is thermodynamically driven. For other metallic nanoparticles, we 440 anticipate that while the general trends will hold, as previously shown,²⁹ the competition 441 442 between different behaviors at various surface densities and size ranges, will depend on their sintering tendencies⁴⁸ and diffusivities in SiO₂.²⁷ 443

The nanopores in oxides formed via the RTP of metal nanoparticles may have 444 applications in sensing,³¹ separations,^{33,34} electronics design,³⁵ and catalysis.^{29,32} In this 445 446 work, we have demonstrated that the average diameter and surface density of the 447 nanopores can be tuned by controlling the average size and distribution of the initial metal 448 nanoparticles. In general, nanopores of similar diameters can be synthesized from two 449 distinct initial nanoparticle distributions, with or without the intervening agglomeration of 450 the nanoparticles. Nanopores formed from a low surface density of large nanoparticles 451 have tunable pore sizes that are comparable to the initial nanoparticle dimensions. However, these nanopores tend to be accompanied by tall oxide ridges which may not 452 453 be desirable in some applications (e.g. a nanopore filtration apparatus). Almost ridge-free 454 nanopores can be achieved via RTP of a high surface density of small nanoparticles that 455 first applomerate and then entrenching producing 10 - 15 nm diameter nanopores. Low 456 surface densities of small nanoparticles can lead to encapsulation and should be avoided

457 if nanopores are desired. Nanopores fabricated in this way have the advantage of 458 requiring only two steps: metal deposition and RTP, and no additional chemical agents. 459 This is in contrast to traditional templated synthesis techniques.⁴⁹ which involve many 460 additional processing steps and potentially costly pore templating agents. The method for 461 nanoparticle synthesis for this purpose is not limited to block copolymer lithography, as shown in this work. A range of different techniques could be employed,^{50–52} if the goal 462 463 were faster and more scalable nanopore synthesis. These findings will help one create 464 designer substrates that could be important in catalysis, molecular separations, and 465 nanoporous device construction. in basically two steps- nanoparticle deposition and RTP, 466 that can be scaled easily.

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Figure 1 AFM images of Pd nanoparticles on a Si-SiO₂ (285 nm) surface A) as synthesized by block copolymer micelle lithography followed by annealing at 150 °C (Ar) and 500 °C (H₂) for 10 h each and B) after RTP at 1040 °C for 10 min using a ramp rate of 3.3 °C/s. C) Pd nanoparticles at different stages of thermal entrenchment after RTP showing i) agglomeration with low oxide ridge formation and without entrenchment, ii) partial entrenchment with oxide ridge formation, iii) near-complete entrenchment with oxide ridge formation, and iv) complete entrenchment (nanopore formation) with oxide ridge formation.

556



Figure 2 A) Tendency to agglomerate (with or without nanopore formation) across different initial nanoparticle distributions after RTP at 1040 °C for 10 min using a ramp rate of 3.3 °C/s. B) Defining different behaviors based on observed pore fraction (f_{Pore}) and extent of agglomeration (E_{Agg}) after RTP.



563 Figure 3 Behaviors (complete and partial entrenchment, encapsulation, and agglomeration) observed as a

564 function of Pd surface area coverage and E_{Agg} of Pd/SiO₂ after RTP at 1040 °C for 10 min using a ramp

565 rate of 3.3 °C/s.



Figure 4 Pd/SiO₂ distributions after RTP at 1040 °C for 10 min using a ramp rate of 3.3 °C/s that result in minimal aggregation (E_{Agg} < 20 %) have surface area coverages less than 15 %. A) In this range, entrenchment, complete or partial, is dominant up to 5% surface area coverage whereas encapsulation is dominant between 5 – 15% coverages. B) Alternately plotted, encapsulation is dominant for smaller nanoparticles sizes (4 – 8 nm) and intermediate surface densities (200 – 500 nanoparticles /µm²), while entrenchment is dominant at larger nanoparticle sizes (6 – 25 nm) and lower surface densities (10 – 250 nanoparticles /µm²). Higher densities of small nanoparticles (not shown) agglomerate, then entrench.





Figure 5 A) AFM images of a Pd/SiO₂ surface i) as synthesized, ii) after RTP at 1040 °C for 10 min using a ramp rate of 3.3 °C/s, iii) after heating the surface in ii for an additional 10 min, and iv) after Pd etching of the surface in iii. B) Surfaces that show encapsulation lose their Pd XPS features after RTP at 1040 °C for 10 min using a ramp rate of 3.3 °C/s.



- 583 Scheme 1 Proposed mechanism of Pd nanoparticle encapsulation within the SiO₂ support by: A)
- 584 nanoparticle encapsulation by oxide ridges before nanopore formation, and B) closing of the nanopores by
- 585 large oxide ridges after entrenchment.



587

Figure 6 A) AFM images of an initially high surface density of small Pd nanoparticles on SiO₂ following
RTP using a ramp rate of 3.3 °C/s and held for 10 min at i) 850, ii) 900, iii) 950, iv) 1000, and v) 1040 °C.
B) Trends in nanoparticle and nanopore surface densities and sizes at each temperature. All inset scale
bars are 20 nm. The nanoparticle surface density and diameter before heating are indicated by the
arrowheads on each axis.



Figure 7 A) AFM images of an initially low surface density of large Pd nanoparticles on SiO₂ following RTP using a ramp rate of 3.3 °C/s and held for 10 min at i) 850, ii) 900, iii) 950, iv) 1000, and v) 1040 °C. B) Trends in nanoparticle and nanopore surface densities and sizes at each temperature. All inset scale bars are 20 nm. The nanoparticle surface density and height before heating are indicated by the arrowheads on each axis.



602 Scheme 2 Proposed behaviors of A) high density of small Pd nanoparticles, and B) low surface density of

603 large Pd nanoparticles at increasing RTP hold temperatures.

604



605

Figure 8 A) AFM images of i) an initially high surface density of small Pd nanoparticles on SiO₂ and ii)
following RTP with ramp of 3.3 °C/s to 1040 °C for 1.5 min, iii) 3 min, and iv) 5 min. B) Trends in nanoparticle

and nanopore surface densities and diameters at each time point. All inset scale bars are 20 nm.





Figure 9 A) AFM images of i) an initially low surface density of large Pd nanoparticles on SiO_2 and ii) following RTP with a ramp of at 3.3 °C/s to 1040 °C for 1.5 min, iii) 3 min, and iv) 5 min. B) Trends in nanoparticle and nanopore surface densities and sizes at each time point. All inset scale bars are 20 nm.



Figure 10 AFM images of A) an initially high surface density of small Pd nanoparticles on SiO₂ following RTP with a 10 min hold at 1040 °C and ramp rates (r_{Ramp}) of i) 0.33, ii) 1, and iii) 3.3 °C/s and B) an initially low surface density of large Pd nanoparticles on SiO₂ following RTP with a 10m in hold at 1040 °C and ramp rates of i) 0.33, ii) 1, and iii) 3.3 °C/s



Figure 11 A) Average nanopore diameter as a function of initial nanoparticle height, B) average oxide ridge height as a function of initial nanoparticle height, and C) number density of nanopores formed as a function of initial number density of Pd nanoparticles. The different extents of agglomeration are also shown. Mild/no agglomeration ($E_{Agg} < 20$ %), Moderate agglomeration ($20\% < E_{Agg} < 80$ %), and Extreme agglomeration ($E_{Agg} > 80$ %).



629 Scheme 3 Proposed temporal evolution of oxide ridges when samples are held above 1000 °C for an initial

630 A) high density of small Pd nanoparticles, and B) low density of large Pd nanoparticles.

1 Mapping the thermal entrenchment behavior of Pd

2 nanoparticles on planar SiO₂ supports

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